

## N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)		
200	0.283 at V <sub>GS</sub> = 10 V	3		

#### **FEATURES**

- Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

• Primary Side Switch



G <b>o</b> –	
N-0	Channel MOSFET

D

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25 \text{ °C}$ , unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	200	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Desig Connect (T 475 °C)	T <sub>C</sub> = 25 °C	L	3		
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 125 °C	I D	2.7		
Pulsed Drain Current	I <sub>DM</sub>	10	A		
Continuous Source Current (Diode Conduction)		۱ <sub>S</sub>		6	
Avalanche Current	I <sub>AS</sub>	6			
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	18	mJ	
Maximum Dawar Dissingtion	T <sub>C</sub> = 25 °C	P <sub>D</sub>	96 <sup>b</sup>	W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>a</sup>	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	t ≤ 10 s	R <sub>thJA</sub>	15	18	°C/W	
Junction-to-Ambient <sup>a</sup>	Steady State		40	50		
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.85	1.1		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.



Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	200		V		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$			50		
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	40			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		0.283 0.320			
	D	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$				0	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C		0.350		Ω	
		$V_{GS} = 6 V, I_D = 3 A$		0.292			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3 A		35		S	
Dynamic <sup>a</sup>		·					
Input Capacitance	C <sub>iss</sub>			1800		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, F = 1 MHz		180			
Reverse Transfer Capacitance	C <sub>rss</sub>			80			
Total Gate Charge <sup>c</sup>	Qg			34	51		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 100 V, $V_{GS}$ = 10 V, $I_{D}$ = 3 A		8		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Gate Resistance	R <sub>g</sub>		0.5		2.9	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 100 V, R <sub>L</sub> = 5.2 $\Omega$		50	75		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 3$ A, $V_{GEN}$ = 10 V, $R_g$ = 2.5 $\Omega$		30	45	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90		
Source-Drain Diode Ratings and Chara	acteristics (1	Γ <sub>C</sub> = 25 °C)		·			
Pulsed Current	I <sub>SM</sub>				5	А	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 3 A, V <sub>GS</sub> = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, dl/dt = 100 A/μs		180	250	ns	

Notes:

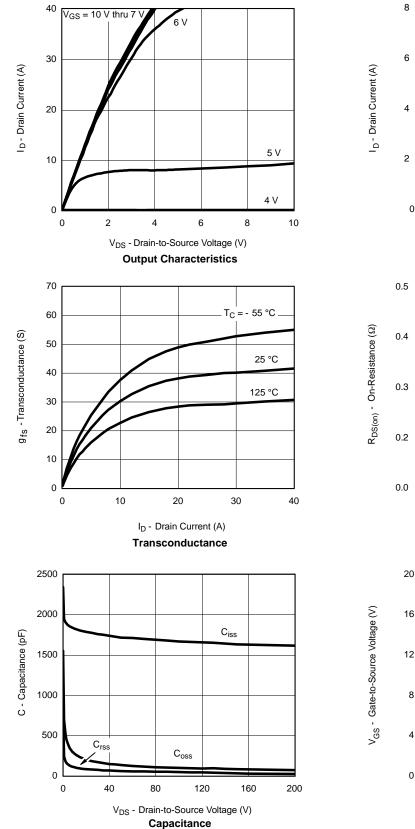
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

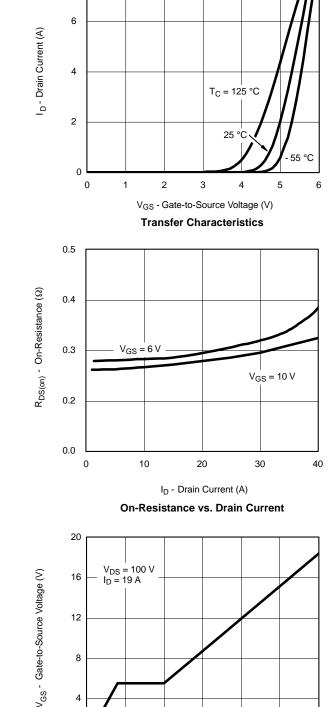
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Q<sub>g</sub> - Total Gate Charge (nC)

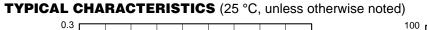
Gate Charge

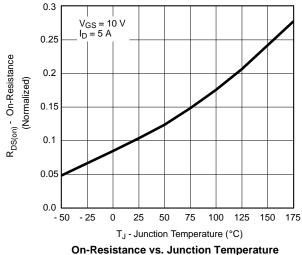


T<sub>J</sub> = 25 °C

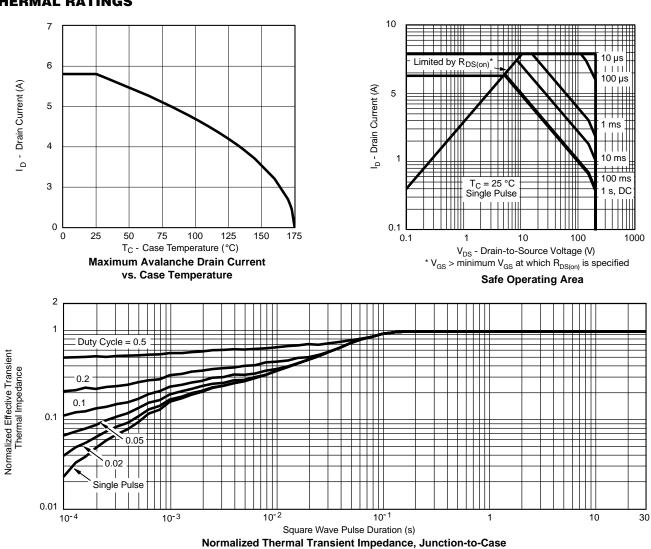
0.9

1.2









I<sub>S</sub> - Source Current (A)

10

1

0

0.3

T<sub>J</sub> = 150 °C

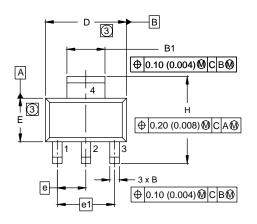
0.6

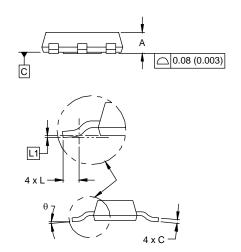
Source-Drain Diode Forward Voltage

V<sub>SD</sub> - Source-to-Drain Voltage (V)



### SOT-223 (HIGH VOLTAGE)





	MILL	IMETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	1.55	1.80	0.061	0.071	
В	0.65	0.85	0.026	0.033	
B1	2.95	3.15	0.116	0.124	
С	0.25	0.35	0.010	0.014	
D	6.30	6.70	0.248	0.264	
E	3.30	3.70	0.130	0.146	
e	2.30 BSC		0.0905 BSC		
e1	4.60 BSC		0.181 BSC		
Н	6.71	7.29	0.264	0.287	
L	0.91	-	0.036	-	
L1	0.061 BSC		0.0024 BSC		
θ	-	10'	-	10'	
ECN: S-82109-Rev. A, 15 DWG: 5969	-Sep-08		•	<u>.</u>	

#### Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Dimensions are shown in millimeters (inches).

3. Dimension do not include mold flash.

4. Outline conforms to JEDEC outline TO-261AA.



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